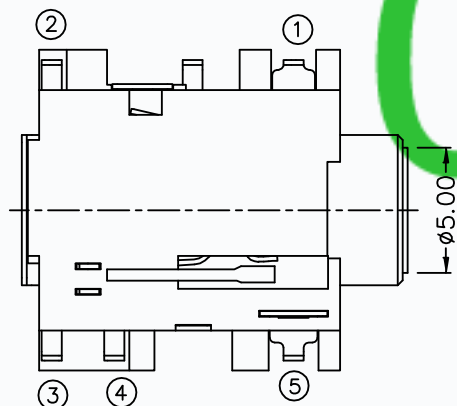
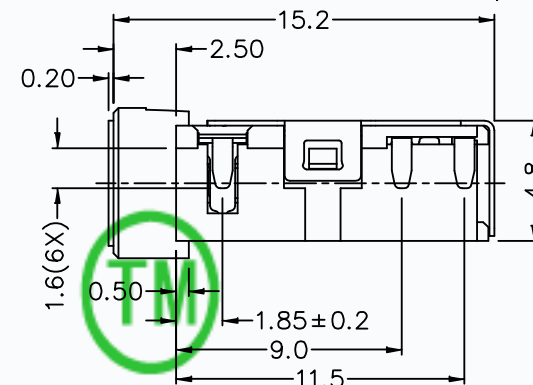
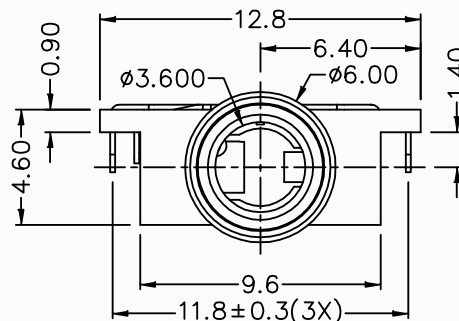
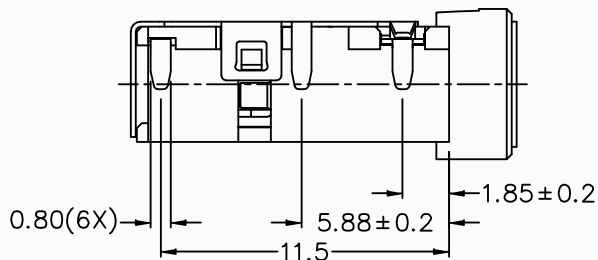
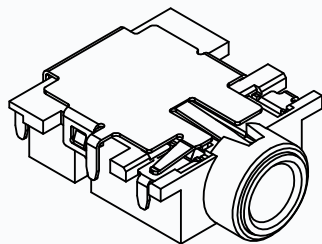


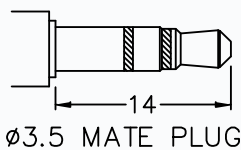
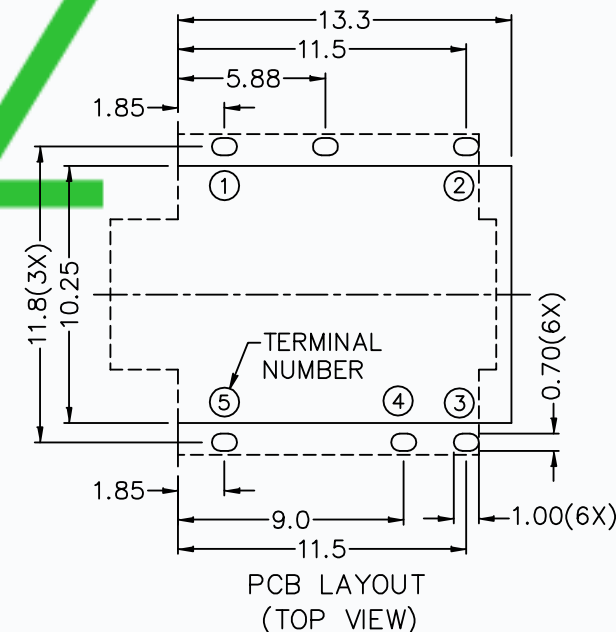
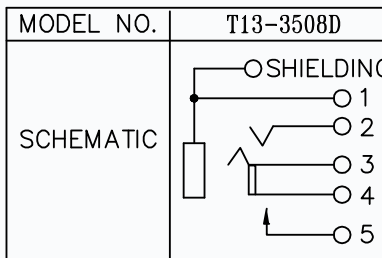
CAD FILE:



# CMTDDZ

**\* MATERIAL**

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 5 : COPPER ALLOY
- SHIELD : COPPER ALLOY
- BUSHING : BRASS
- HOUSING : PA9T



		<b>TOLERANCE UNLESS SPECIFIED</b> WITHIN 1.5mm : ±0.1mm OVER 1.5mm : ±0.2mm	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF DONGGUAN TIANDU ELECTRONICS CO.,LTD. AND SHALL NOT BE REPRODUCED. COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF DONGGUAN TIANDU ELECTRONICS CO., LTD	<b>TITLE : 3.5mm SMD PHONE JACK</b>		<b>UNIT : mm</b>		<b>DRWG NO.: CMTDDZ-T13-3508D-00</b>		
				<b>MODEL: T13-3508D</b>		<b>SCALE: 3:1</b>		<b>DWN.</b>	<b>ERIC</b>	<b>2013-6-17</b>
				<b>CMTDDZ 东莞市田都电子有限公司</b>			<b>CHK'D</b>	<b>MAIKO</b>	<b>2013-6-17</b>	
<b>APPD.</b>		<b>DESCRIPTIONS OF REVISION</b>		<b>DONGGUAN TIANDU ELECTRONICS CO.,LTD.</b>			<b>APPD.</b>	<b>Coco</b>	<b>2013-6-17</b>	